

4225945/C 08/2025

NOTES:

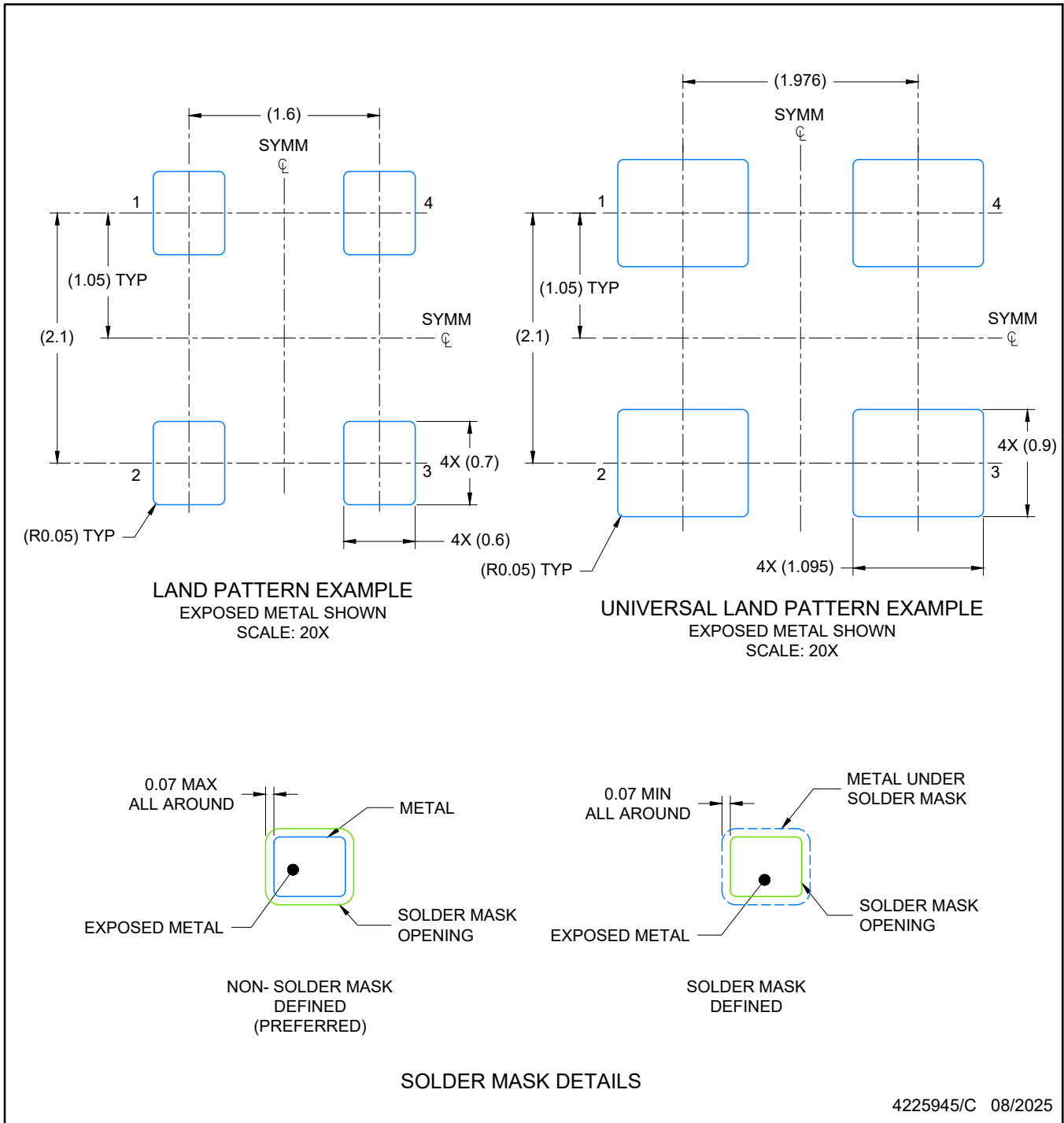
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

EXAMPLE BOARD LAYOUT

VSON - 1 mm max height

DLE0004A

PLASTIC QUAD FLAT PACK-NO LEAD



NOTES: (continued)

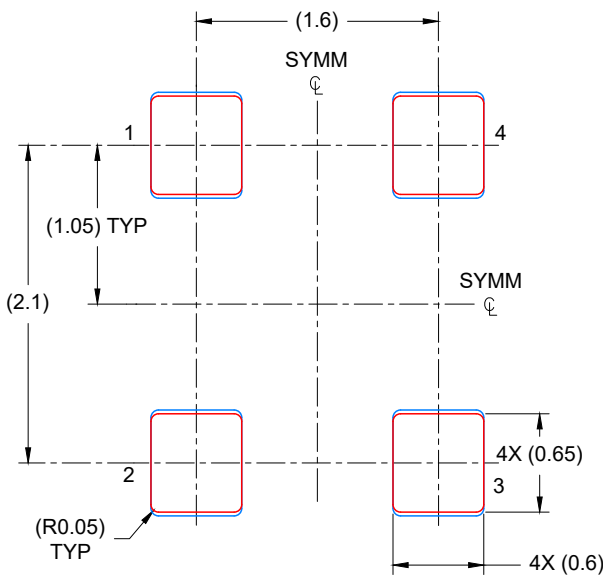
- For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/sl原因271) .

EXAMPLE STENCIL DESIGN

VSON - 1 mm max height

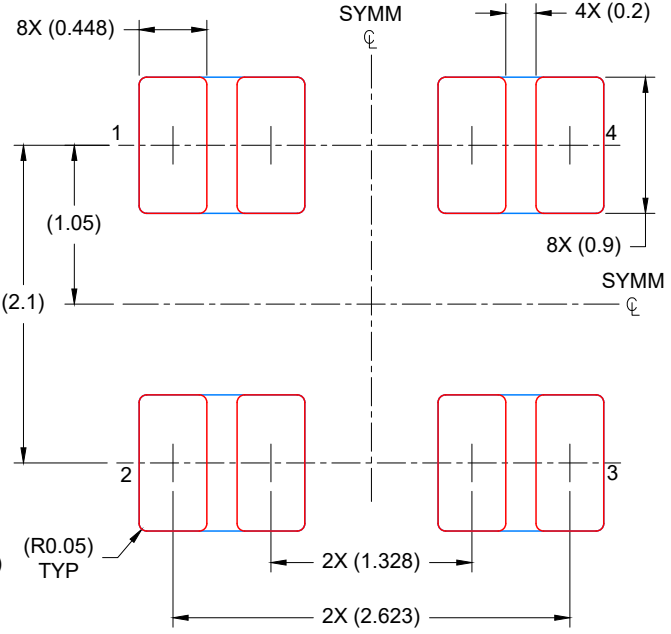
DLE0004A

PLASTIC QUAD FLAT PACK-NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
ALL PADS: 93%
SCALE: 20X



UNIVERSAL SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
ALL PADS: 82%
SCALE: 20X

4225945/C 08/2025

NOTES: (continued)

- 4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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